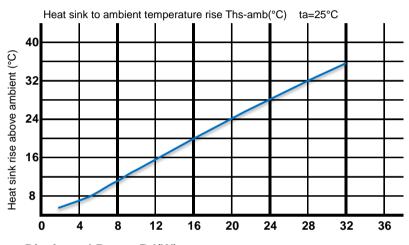


The thermal data table

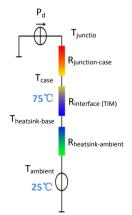
Pd=Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb(°C/W)	Heat sink to ambient temperature rise Ths-amb(°C)
		Eden-4001E	
Dissipated Power Pd(W)	2	1.45	3.3
	5	1.36	7.8
	10	1.12	13.2
	15	1.08	19.2
	20	1.03	24.5
	25	0.96	29
	30	0.93	34



Dissipated Power Pd(W)

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;
- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.
- Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- $\theta\,$ Thermal Resistance [°C/W] ; Ths - Heatsink temperature ; Ta - Ambient temperature ;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer
- shell is $R_{\text{junction-case}}$, the thermal resistance of the TIM outside the package is $R_{\text{interface (TIM)}}$ [°C/W], the thermal resistance with the
- heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].
- *Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:
- $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$